**NOTES**

1. **MATERIALS:**
   LEAD FRAME: COPPER 194FH, THK = 0.008
   BODY: SEMICONDUCTOR MOLDING EPOXY, CONTACT QPTECHNOLOGIES FOR DETAILS.

2. **FINISH:**
   LEAD FRAME: ELECTROLESS NICKEL PER MIL-C-26074, CLASS 1,
   250 TO 300 MICROINCHES (6.25um-7.6um) THICK.
   GOLD PLATE PER MIL-G-45204, TYPE 3, GRADE A, CLASS 1
   (40 TO 80 MICROINCHES (1um-2um) THICK).
   BODY SURFACE FINISH: VDI 21-24 (1.12-1.6 Ra)

3. **PACKAGE MISMATCH:** BODY OFFSET FOR LEAD FRAME = 0.076mm MAX.

4. **UNLESS OTHERWISE SPECIFIED:** RADIUS ON ALL MOLDED EDGES
   AND CORNERS = 0.25mm MAX.

5. **PACKAGE CONFORMS TO JEDEC MO-220**